

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, May 19, 2012 03:59 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mf Item Number	Mf Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
GBPC2504W	GBPC2504W	GBPC-W			SUBCONTRACTOR	17.003	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom
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RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted
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Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC
 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name GBPC-W

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Casing	Other Organic Materials	7420.000	Supplier		Epoxy Resin	7420.000	29690-82-2	436385
Chip	Other inorganic materials	27.200	Supplier		Silicon	27.200	7440-21-3	1600
Encapsulation	Thermoplastics	7475.700	B	Antimony/Antimony Compounds	Antimony Trioxide	86.700	1309-64-4	5099
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	137.000	6386-73-8	8057
			Supplier		Carbon Black	62.000	1333-86-4	3646
			Supplier		Cycloaliphatic Anhydride	1270.000	19438-60-9	74691
			Supplier		Epoxy Resin	1800.000	29690-82-2	105862
			Supplier		Silica, vitreous	4120.000	60676-86-0	242305
Ink	Other Organic Materials	4.200	Supplier		Dye	0.630	7429-90-5	37
			Supplier		Silicon	0.105	112945-52-5	6
			Supplier		Synthetic resin	2.940	53192-18-0	173
			Supplier		additive	0.105	947-19-3	6
			Supplier		opto agent	0.420	21245-01-2	25
Slug	Copper & its alloys	1160.000	Supplier		Copper	1160.000	7440-50-8	68222
Solder Paste	Other Nonferrous metals & alloys	20.000	A	Lead/Lead Compounds	Lead	18.500	7439-92-1	1088
			Supplier		Silver	0.500	7440-22-4	29
			Supplier		Tin	1.000	7440-31-5	59
Solder Wafer	Other Nonferrous metals & alloys	49.400	A	Lead/Lead Compounds	Lead	45.700	7439-92-1	2688
			Supplier		Silver	1.230	7440-22-4	72
			Supplier		Tin	2.470	7440-31-5	145
Wire Bond	Copper & its alloys	846.847	Supplier		Copper	846.000	7440-50-8	49755
			Supplier		Silver	0.847	7440-22-4	50